

产品规格承认书

SPECIFICATIONS

Manufacturer: Shenzhen guo-link Technology Co., Ltd.Address: Room 10102,Workshop 4,No.1 Road,ShangxueTechnology City,Xinxue Community,Bantian Sub-district,Longgang District,Shenzhen City,China

CUSTOMER PART No: _____

产品型号:

OUR MODEL NO: PBX3216HC01

日期:

DATE: _____

确认签字, 盖章后请返回承认书一份

PLEASE RETURN TO US ONE COPY OF "SPECIFICATION FOR APPROVAL"

WITH YOUR APPROVED SIGNATURES

Approved	LiuFei	Audit	LiuFei	Making	LiuXiaoMei
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Customer Acknowledges Signature

Date

UNLESS OTHER SPECIFIED TOLERANCES ON:

X=±

X.X=±

X.XX=

ANGLES = ±

HOLE DIA = ±



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SCALE: N/A

UNIT: mm

DRAWN BY: Sera

CHECKED BY: XD

DESIGNED BY: Sera

APPROVED BY: XD

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TITLE: CHIP2450-3216 Specification

DOCUMENT
NO.

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PBX3216HC01 Specification

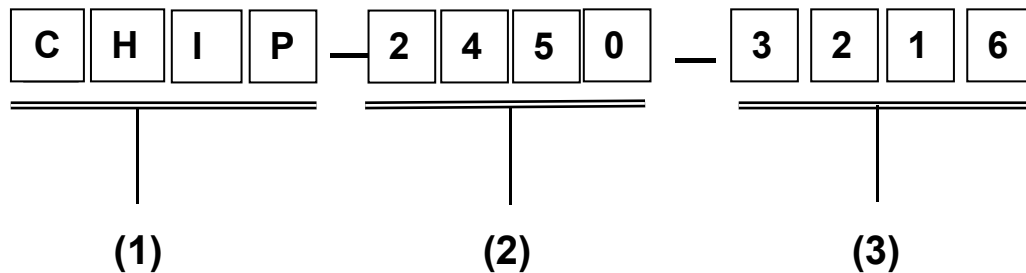
Operating Temp. : -40℃~+85℃

1. FEATURES:

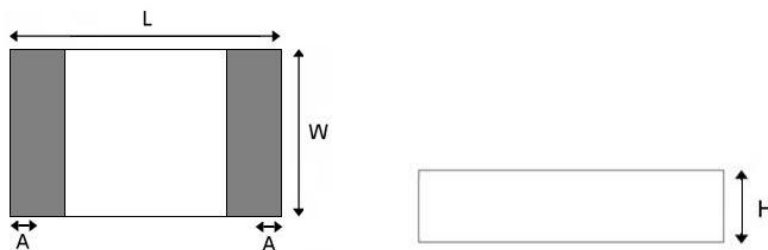
- Light weight, compact
- Wide bandwidth, low cost
- Built-in antenna with high gain

2. APPLICATIONS:

- Bluetooth, Wireless LAN, Mobile TV
- Home RF System, etc

3. PRODUCT IDENTIFICATION

- (1) Product type: Multilayer chip Antenna
 (2) Center Frequency: 2450MHz
 (3) External Dimensions (L×W) (mm): 3.2*1.6

4. SHAPE AND DIMENSIONS:

L	W	H	A
3.2±0.2	1.6±0.2	0.52±0.1	0.4±0.1

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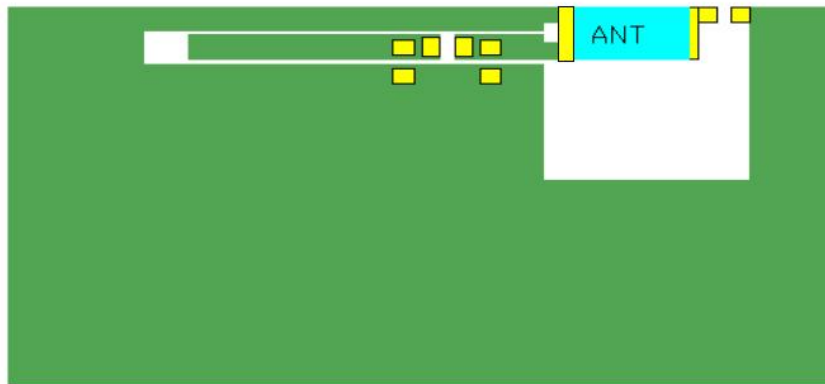
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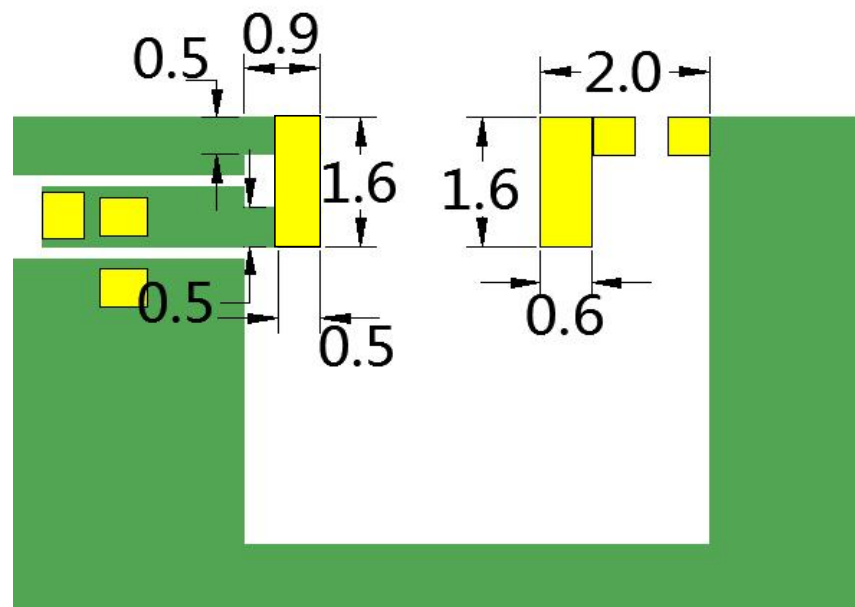
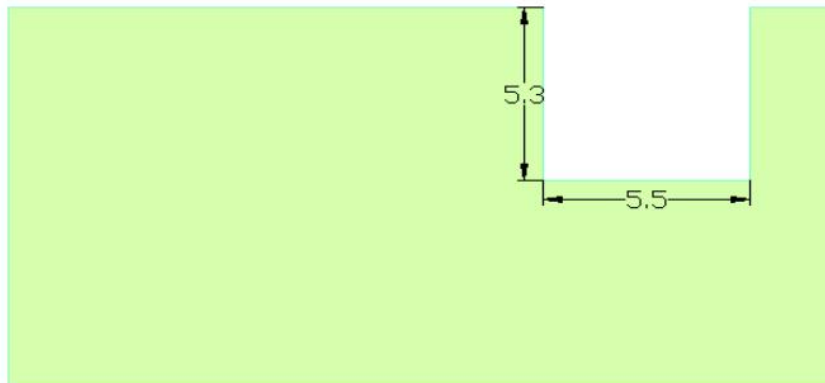
P1

Test plate reference size:

Company: mm



- Antenna
- PAD
- Copper laying on the bottom layer
- Top layer copper laying



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ANGLES = \pm HOLEDIA = \pm



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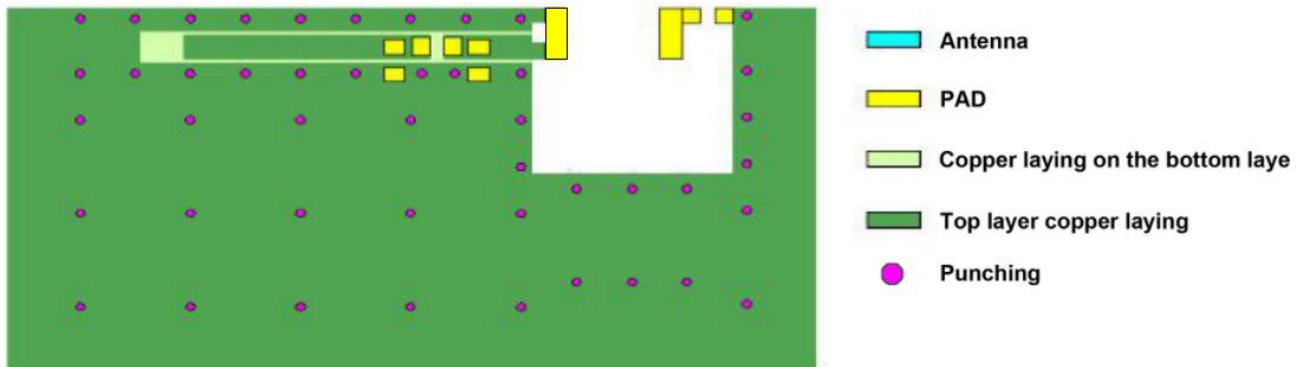
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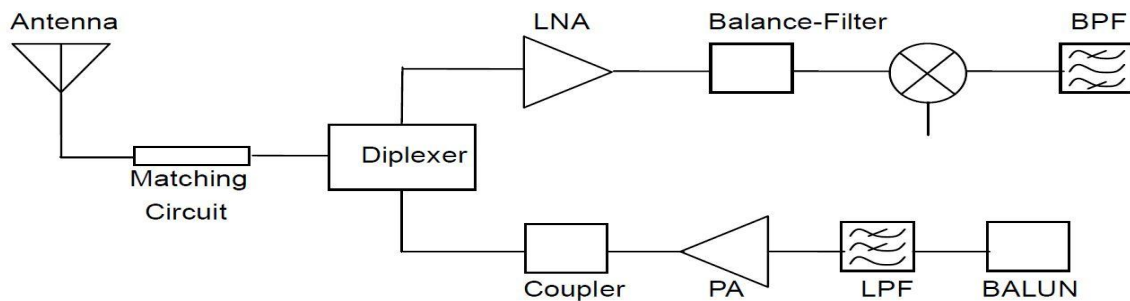
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Hole punching reference diagram



APPLICATION GUIDE



5. SPECIFICATIONS:

Test Item	Specifications
Bandwidth	2400-2483MHz
Polarization mode	Linear polarization
* Maximum gain	2.67dBi
* Efficiency	72.3%
Input Impedance	50Ω

* Test condition: Test board size 90*40 mm

Matching circuit: Pi matching circuit will be required

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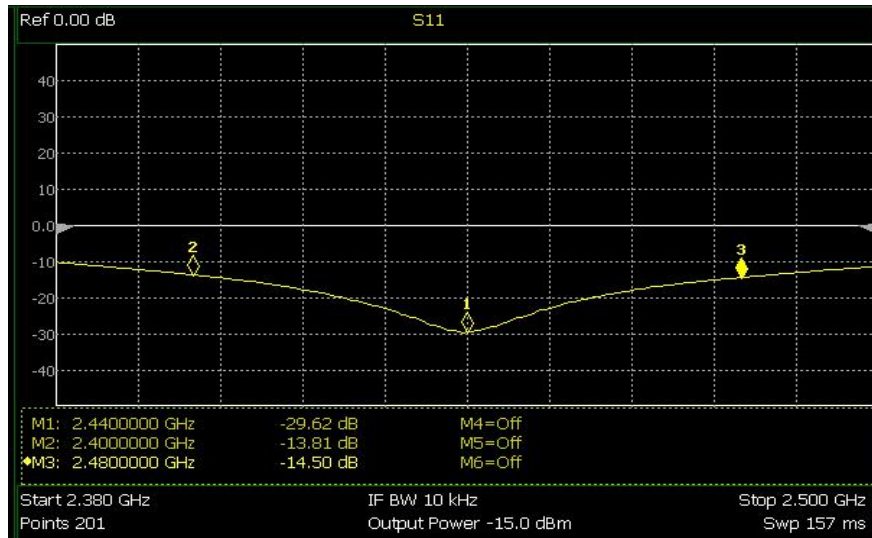
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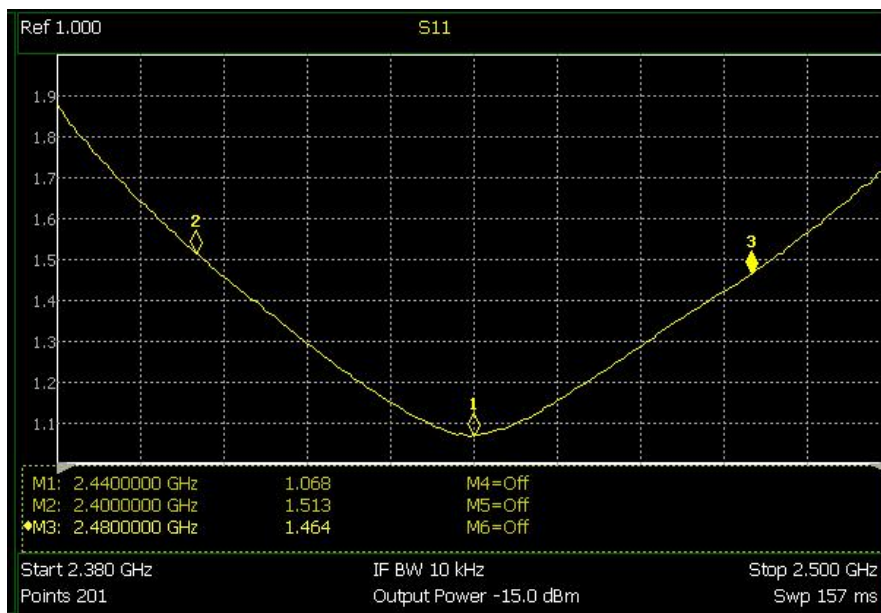
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6. Electrical Characteristics :

Return loss



Standing wave ratio



Mark	Frequency	VSWR
1	2400 MHz	1.513
2	2440 MHz	1.068
3	2480 MHz	1.464

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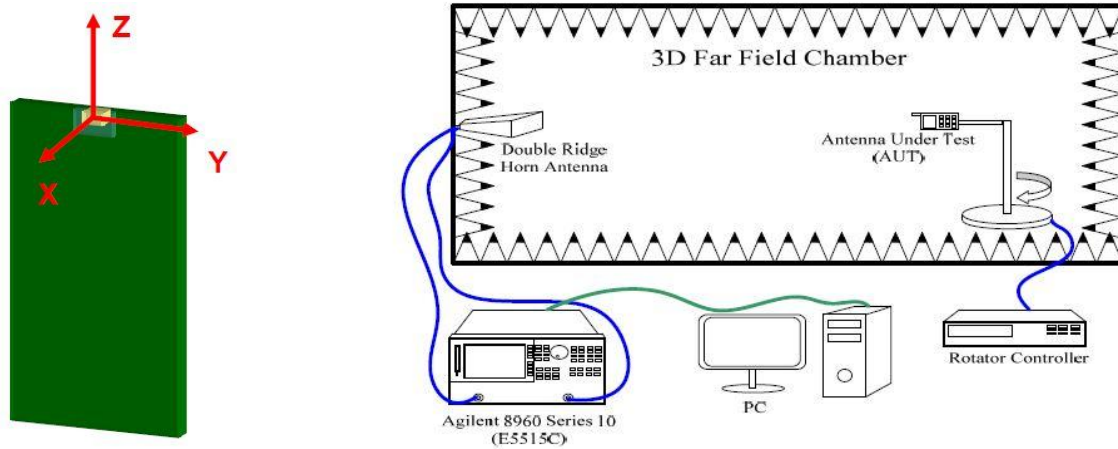
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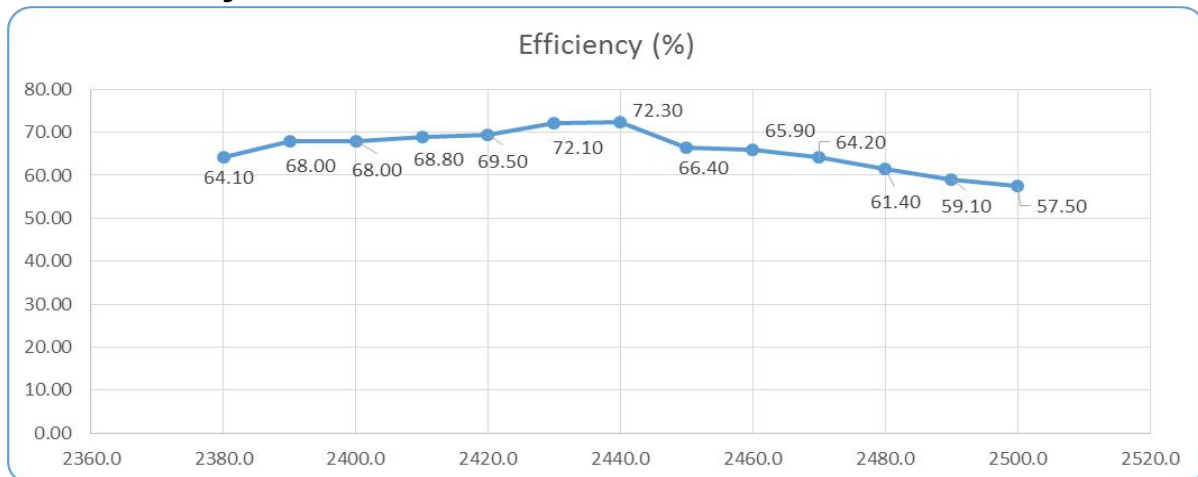
P1

Radiation Pattern

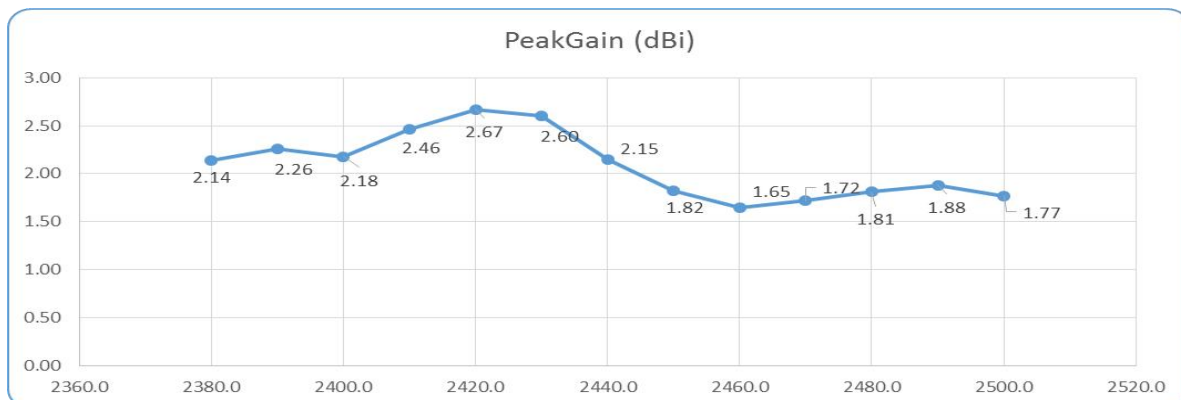
The Gain pattern is measured in FAR-field chamber. DUT is placed on the table of rotator,a standard horn antenna and Vector Network Analyzer is used to collect data.



Efficiency



Maximum gain



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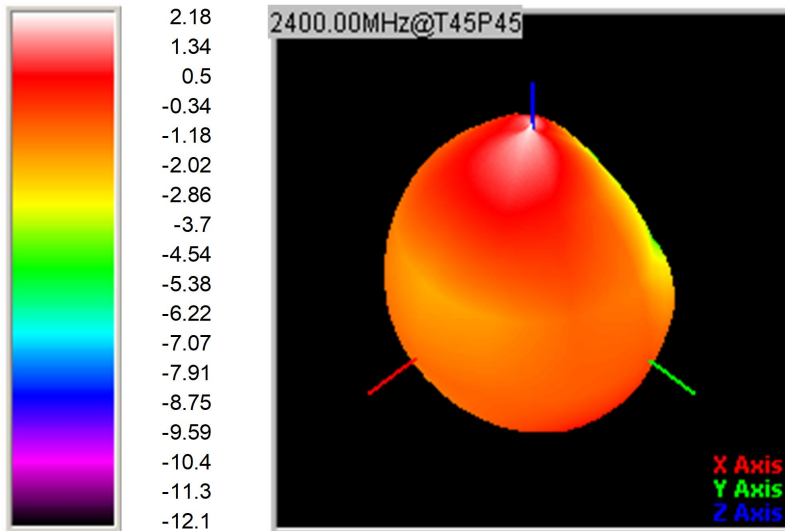
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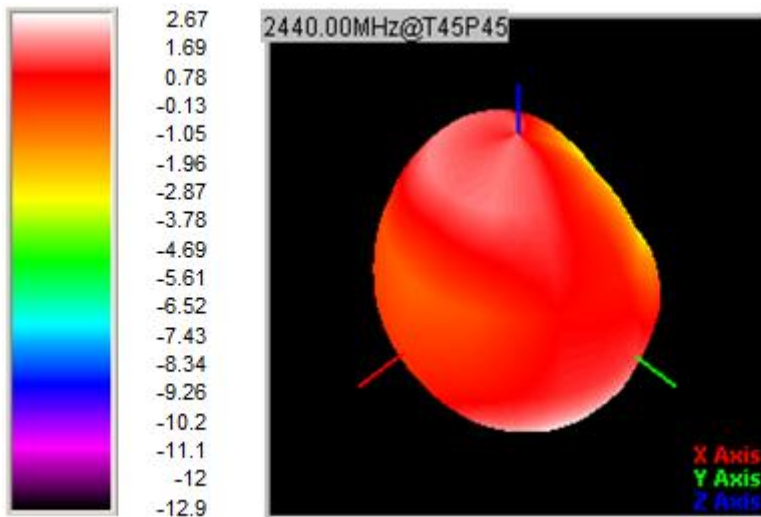
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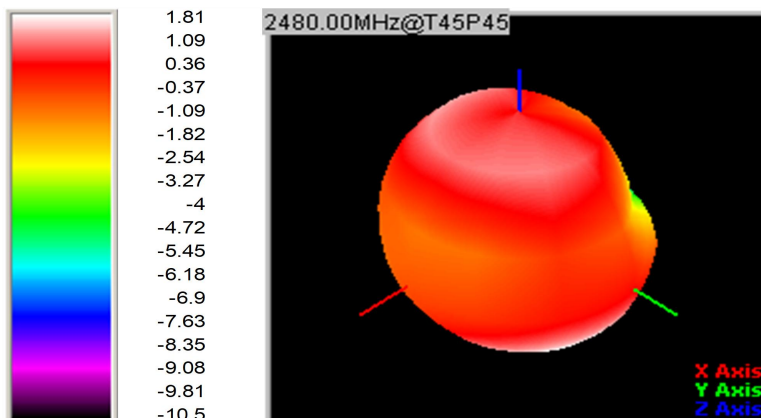
◎ 3D Gain Pattern (2400 MHz)



◎ 3D Gain Pattern (2440 MHz)



◎ 3D Gain Pattern (2480 MHz)



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7. Environmental Characteristics

(1) Reliability Test

Item	Condition	Specification
Thermal shock	1. 30 ± 3 minutes at $-40^{\circ}\text{C}\pm5^{\circ}\text{C}$, 2. Convert to $+105^{\circ}\text{C}$ (5 minutes) 3. 30 ± 3 minutes at $+105^{\circ}\text{C}\pm5^{\circ}\text{C}$, 4. Convert to -40°C (5 minutes) 5. Total 100 continuous cycles	No apparent damage Fulfill the electrical spec. after test.
Humidity resistance	1. Humidity: 85% R.H. 2. Temperature: $85\pm5^{\circ}\text{C}$ 3. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
High temperature resistance	1. Temperature: $150^{\circ}\text{C}\pm5^{\circ}\text{C}$ 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Low temperature resistance	1. Temperature: $-40^{\circ}\text{C}\pm5^{\circ}\text{C}$ 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Soldering heat resistance	1. Solder bath temperature : $260\pm5^{\circ}\text{C}$ 2. Bathing time: 10 ± 1 seconds	No apparent damage
Solderability	The dipped surface of the terminal shall be at least 95% covered with solder after dipped in solder bath of $245\pm5^{\circ}\text{C}$ for 3 ± 1 seconds.	No apparent damage

(2) Storage Condition

(a) At warehouse:

The temperature should be within $0\sim30^{\circ}\text{C}$ and humidity should be less than 60% RH.

The product should be used within 1 year from the time of delivery.

(b) On board:

The temperature should be within $-40\sim85^{\circ}\text{C}$ and humidity should be less than 85% RH.

(3) Operating Temperature Range

Operating temperature range : -40°C to $+105^{\circ}\text{C}$.

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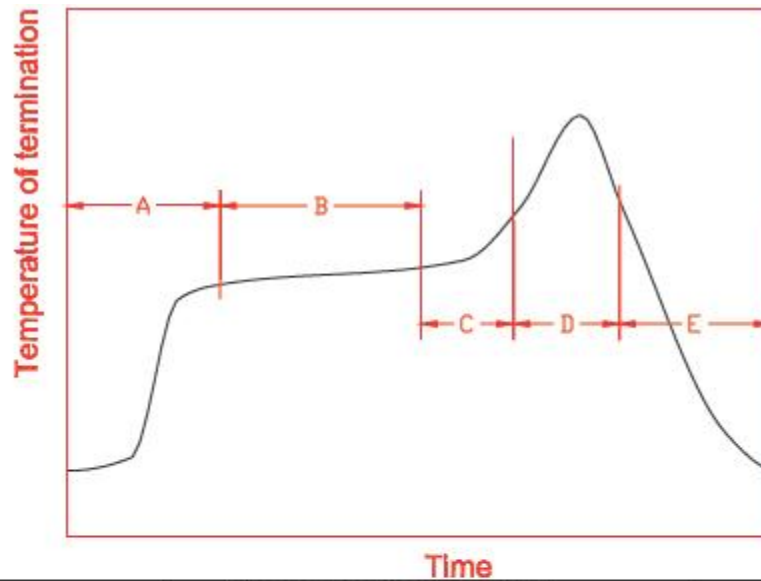
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8. Recommended Reflow Soldering



A	1 st rising temperature	The normal to Preheating temperature	30s to 60s
B	Preheating	140°C to 160°C	60s to 120s
C	2 nd rising temperature	Preheating to 200°C	20s to 40s
D	Main heating	if 220°C	50s~60s
		if 230°C	40s~50s
		if 240°C	30s~40s
		if 250°C	20s~40s
		if 260°C	20s~40s
E	Regular cooling	200°C to 100°C	1°C/s ~ 4°C/s

*reference: J-STD-020C


(1) Soldering Gun Procedure

Note the follows, in case of using solder gun for replacement.

- The tip temperature must be less than 350° C for the period within 3 seconds by using soldering gun under 30 W.
- The soldering gun tip shall not touch this product directly.

(2) Soldering Volume

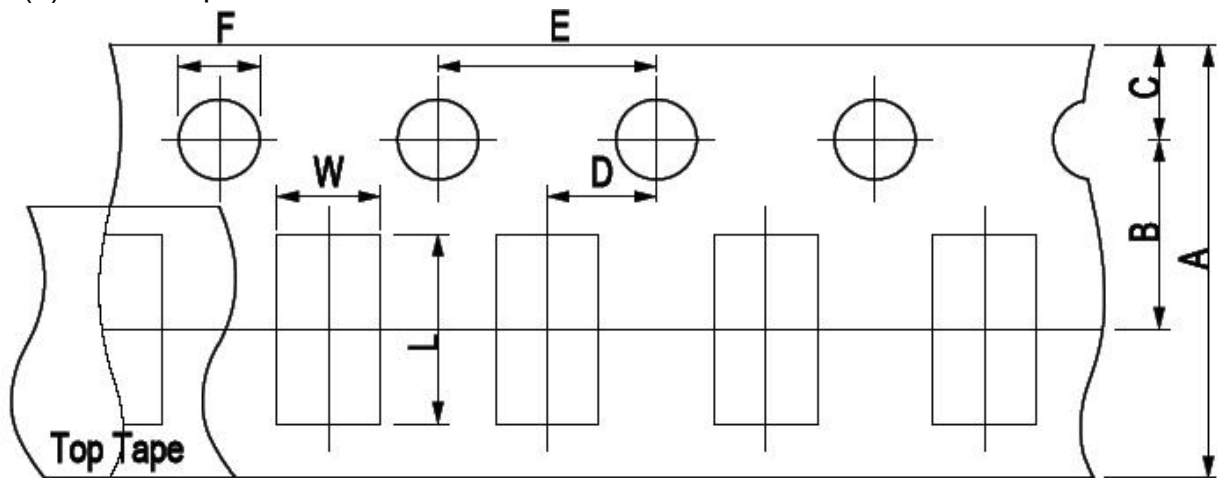
Note that excess of soldering volume will easily get crack the body of this product.

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9. Taping Package and Label Marking: (unit: mm)

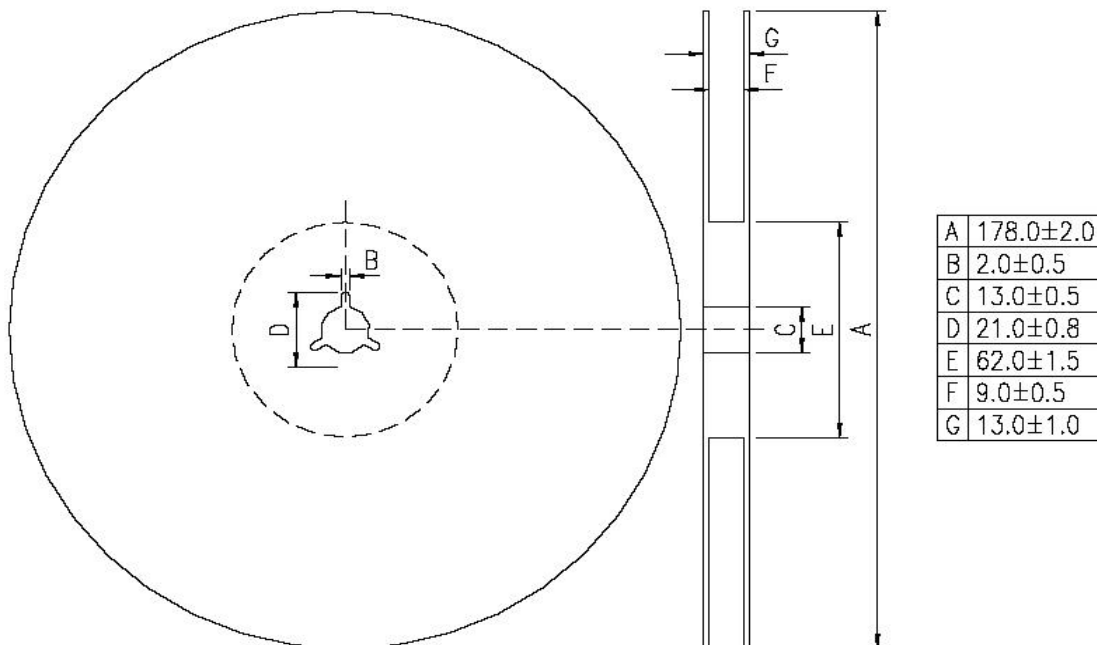
(1) Quantity/Reel: 5000pcs/Reel

(2) Carrier tape dimensions



Type	A	B	C	D	E	F	L	W
2450-21	8.00 ± 0.3	3.50 ± 0.05	1.75 ± 0.1	2.00 ± 0.05	4.00 ± 0.1	1.50 ± 0.1	2.30 ± 0.1	1.55 ± 0.1

(3) Taping reel dimensions



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